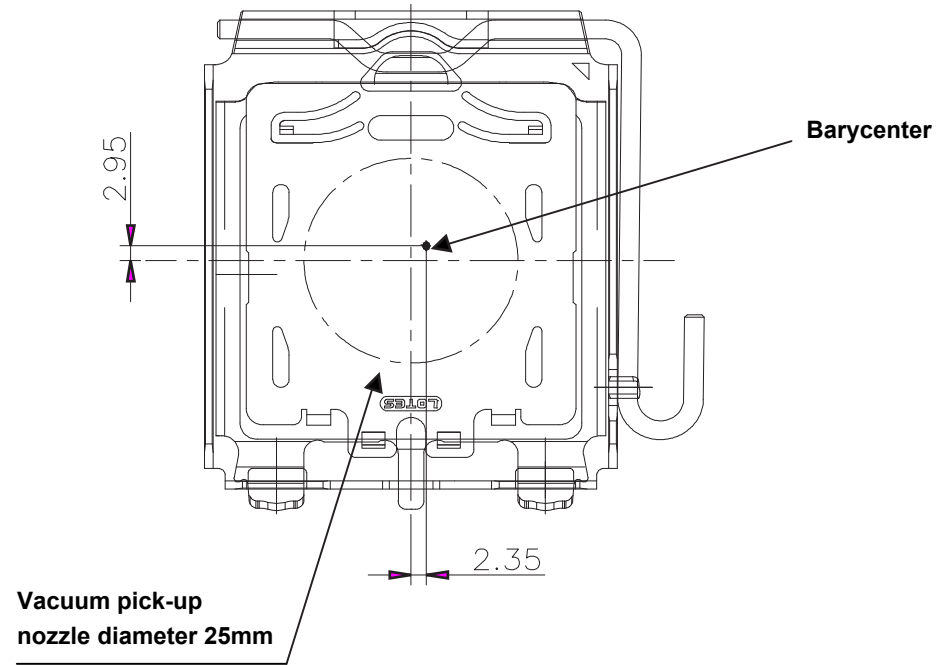
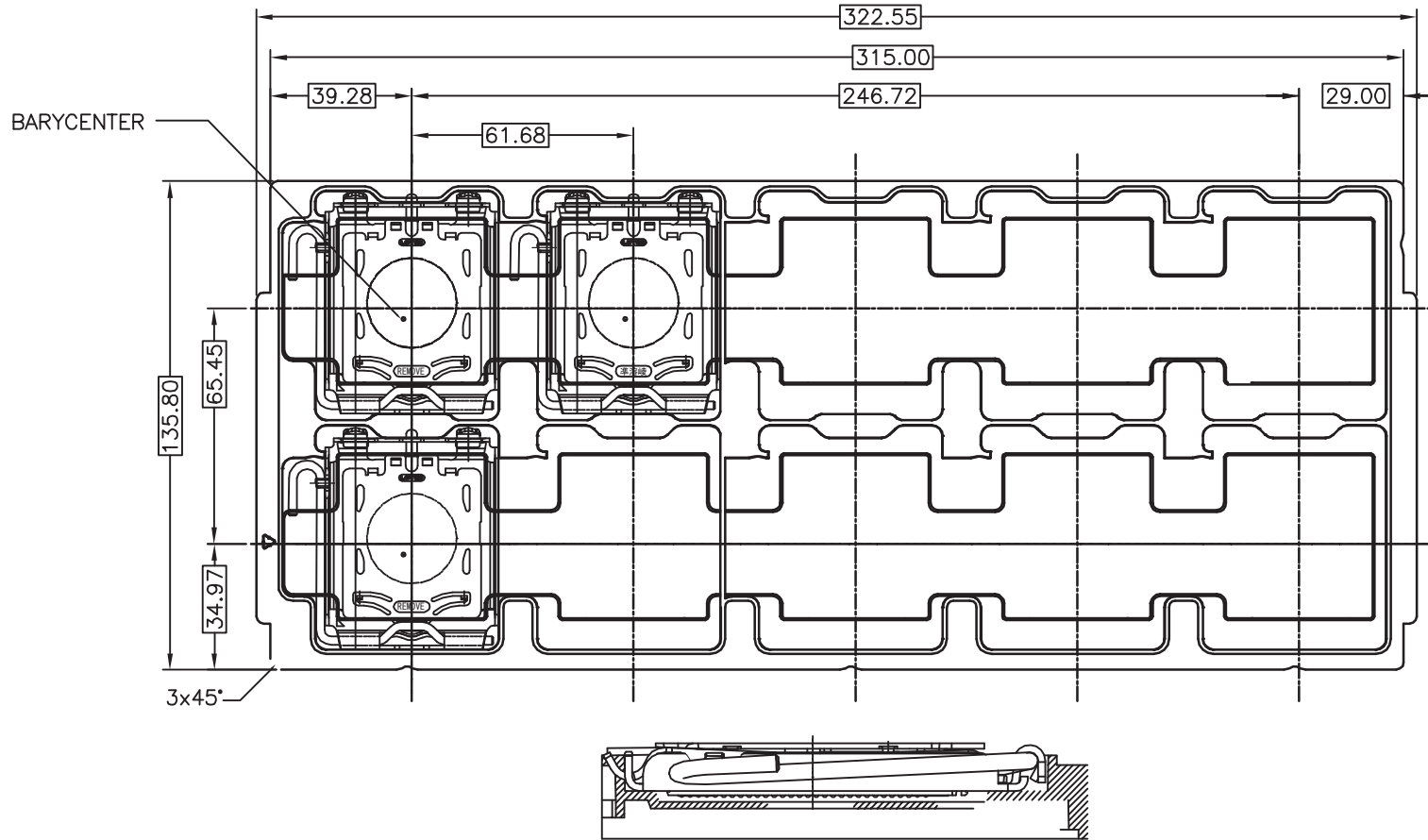


Recommended pick-up position & nozzle size



Rev	Drawn	Checked	Approved	Date	SMP TECHNOLOGY, INC.
0 Issued	WHS	S.M.	S.M.	9/18/06	
					CPU Socket, 775 Position
SCALE: N/A					
TOL. DEC.	.X +/- 0.35	.XX +/- 0.25	.XXX +/- 0.15	ANGLE +/- 3°	UNIT: mm
SERIES: ZF41-7751-10X-Z					Pg: 1 of 5



MATERIAL:

1. BASE HOUSING: THERMOPLASTIC UL94V-0
2. COVER: THERMOPLASTIC UL94V-0
3. CONTACT: COPPER ALLOY
FINISH: GOLD PLATING OVER 50 μ m MIN. NICKEL UNDER PLATING ON CONTACT AREA
4. SOLDER BALL: Sn63%/Pb37%
5. HANDLE: SUS 304
6. STIFFENER: STAINLESS STEEL
7. LOAD PLATE: STAINLESS STEEL

Rev	Drawn	Checked	Approved	Date
0	WHS	S.M.	S.M.	9/18/06
Issued				

SMP TECHNOLOGY, INC.

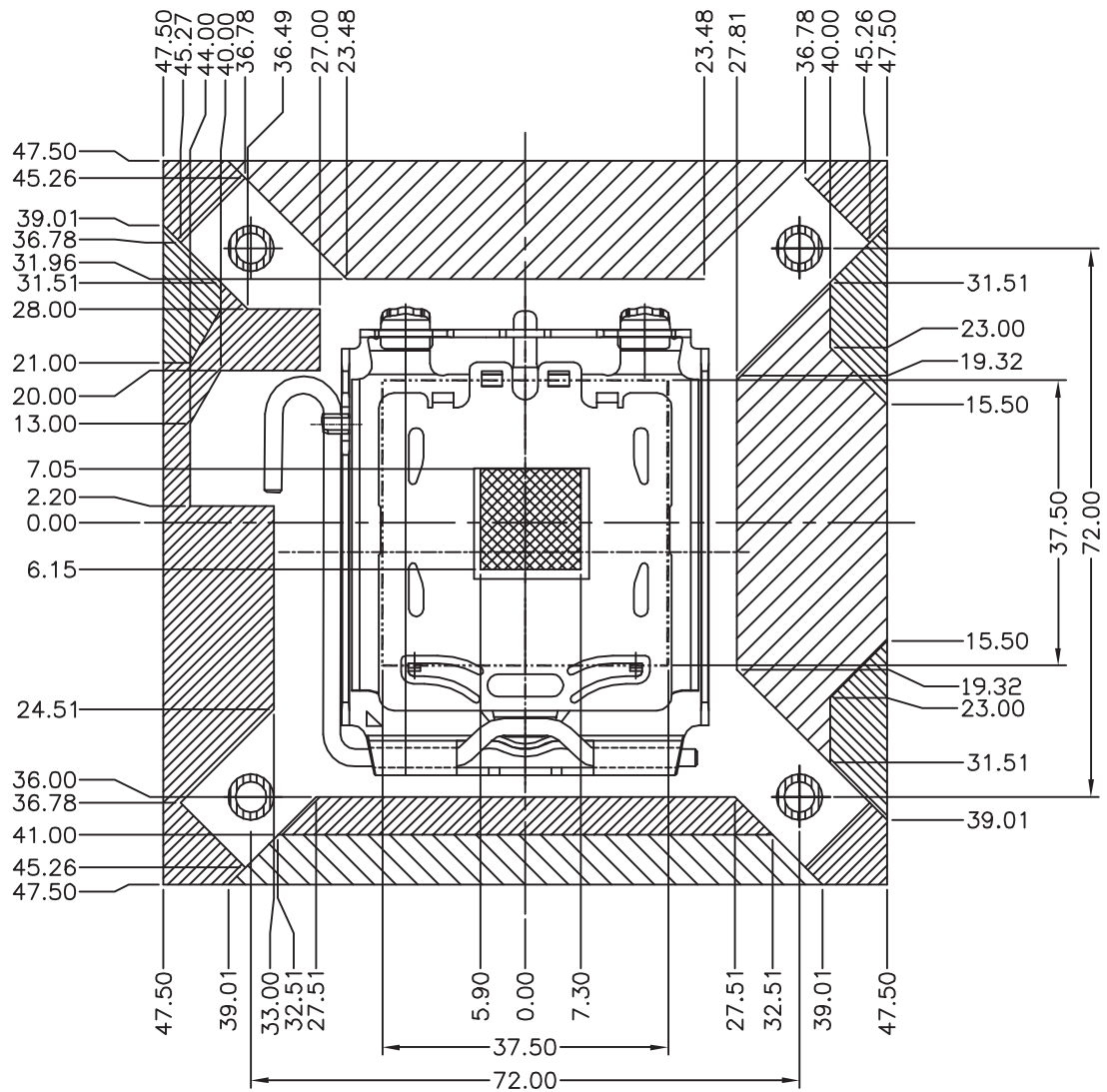
CPU Socket, 775 Position

SCALE: N/A

TOL. DEC. .X +/- 0.35 .XX +/- 0.25 .XXX +/- 0.15 ANGLE +/- 3° UNIT: mm

SERIES: ZF41-7751-10X-Z

Pg: 2 of 5



RECOMMENDED PC BOARD KEEPOUT

LEGEND	
	SOCKET/THERMO/MECHANICAL COMPONENT KEEP-INS
	10.0mm MAX. COMPONENT HEIGHT
	2.5mm MAX. COMPONENT HEIGHT
	6.0mm MAX. COMPONENT HEIGHT
	25.0mm MAX. COMPONENT HEIGHT
	1.8mm MAX. COMPONENT HEIGHT
	BOARD ROUTING KEEP-OUT

Rev	Drawn	Checked	Approved	Date
0 Issued	WHS	S.M.	S.M.	9/18/06

SMP TECHNOLOGY, INC.

CPU Socket, 775 Position

SCALE: N/A

TOL. DEC. .X +/- 0.35 .XX +/- 0.25 .XXX +/- 0.15 ANGLE +/- 3° UNIT: mm

